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(54) **MODULE-TO-MODULE MECHANICAL,  
ELECTRICAL, AND AIRFLOW  
CONNECTIONS IN MODULAR DATA  
CENTERS**

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(57) **ABSTRACT**

A modular data center includes: a modular information technology component (MITC), in which the MITC includes a plurality of information handling systems (IHSs), a utility control component (UCC), and a first connection interface, in which the first connection interface includes a first set of mechanical and electrical connection components (MECCOMs); and a modular environmental control component (MECC), in which the MECC includes a plurality of environmental control components (ECCs) and a second connection interface, in which the second connection interface includes a second set of MECCOMs to be paired with the first set of MECCOMs to generate at least a portion of the modular data center; and in which the first connection interface is connected to the second connection interface, in which an area enclosed by the first connection interface is equal to an area enclosed by the second connection interface.

